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Pixus Announces New 9U RiCool OpenVPX Chassis With Superior Cooling

Waterloo, Ontario — Jan 16, 2018 Pixus Technologies, a provider of embedded computing and enclosure solutions, now offers over 392 CFM (cubic feet per minute) of airflow in a front-to-rear cooled rackmount chassis platform.

The 9U RiCoolTM chassis platform features up to 32 OpenVPX backplane slots in the 3U size and up to 16 slots accommodating 6U cards. Powerful reverse impeller blowers reside directly above the boards. They pull air from below the card cage and blow the exhaust 90 degrees out the back. This allows the use of RTMs (rear transition modules) without adding chassis height. The fans are individually hot swappable, enhancing reliability and minimizing downtime.

The Pixus RiCool chassis platforms feature various power supply options, including fixed, pluggable and redundant options. As experts in high-performance backplane design, the OpenVPX versions come in PCIe Gen3 or 40GbE speeds and beyond. OpenVPX shelf managers and VITA 62 power interface boards are optional.

Pixus provides OpenVPX chassis platforms in various front-to-rear, side-to-side, and bottom-to-top airflow configurations. The company also offers system platforms in CompactPCI Serial, MicroTCA, AdvancedTCA, VME64x and customized architectures.

About Pixus Technologies

Leveraging over 20 years of innovative standard products, the Pixus team is comprised of industry experts in electronics packaging. Founded in 2009 by senior management from Kaparel Corporation, a Rittal company, Pixus Technologies' embedded backplanes and systems are focused primarily on ATCA, OpenVPX, MicroTCA, and custom designs. Pixus also has an extensive offering of VME-based and cPCI-based solutions. In May 2011, Pixus Technologies became the sole authorized North and South American supplier of the electronic packaging products previously offered by Kaparel Corporation and Rittal.